

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

SAH
#4A
7-601

Pri rity Application Serial No. 09/449,025

Pri rity Filing Date November 24, 1999

Inventor Shozo Nagano et al.

Assignee Honeywell International, Inc.

Priority Group Art Unit 1775-1792

Examiner Unknown

Attorney's Docket No. 30-5000-(4015)-Div1

Title: Conductive Integrated Circuit Metal Alloy Interconnections, Electroplating Anodes, Metal Alloys for Use as a Conductive Interconnection in an Integrated Circuit; and Physical Vapor Deposition Targets

PRELIMINARY AMENDMENT

To: Box Patent Application
Assistant Commissioner for Patents
Washington, D.C. 20231

From: Mark S. Matkin (Tel. 509-624-4276; Fax 509-838-3424)
Wells, St. John, Roberts, Gregory & Matkin P.S.
601 West First Avenue, Suite 1300
Spokane, WA 99201-3817

Sir:

Please enter the following amendments prior to examining the above-identified application.

AMENDMENTS

In the Title

Please replace the title with the following: CONDUCTIVE INTEGRATED CIRCUIT METAL ALLOY INTERCONNECTIONS, ELECTROPLATING ANODES; METAL ALLOYS FOR USE AS A CONDUCTIVE INTERCONNECTION IN AN INTEGRATED CIRCUIT; AND PHYSICAL VAPOR DEPOSITION TARGETS.--